**AE427** 



#### **Product Features**

- Small size
- 5MHz-1000MHz
- High gain
- High linearity
- Higher productivity
- Low cost

### **Applications**

- Low Noise Amplifier for CATV, Satellite
- Cable Modem
- FTTH (G-PON, GE-PON)
- Optical node



Package Type: SOT-89

## **Description**

AE427 is designed as low cost drive amplifiers for many applications including FTTH, CATV System. This MMIC is based on Gallium Arsenide Enhancement Mode pHEMT which shows low current draw and very low noise. The data in this spec sheet is valid only for 75 ohm application. 50 ohm data is in a separate spec sheet.

#### **Electrical Specifications**

PARAM	<b>METER</b>	UNIT	MIN	TYP	MAX	CONDITION
Frequ	iency	MHz	5	-	1000	-
Ga	nin	dB	23 24	25 26	-	$30 \sim 1000 MHz$ $5 \sim 200 MHz$
Gain F	latness	dB	, '	0.45	1	$30\sim1000MHz$
Input Re	Input Return Loss		1	-15	1	-
Output Return Loss		dB	1	-15	-	-
Output IP3		dBm	38	41	-	@ 500MHz/5dBm 2tone
1dB Compr	1dB Compression Point		22	24	-	@500MHz
Noise :	Noise Figure		1	2	3	$30 \sim 1000 MHz$
CSO		dBc	-	-56	-	
CTB 50 ~ 870MHz		dBc	-	-71	-	135Channel@30dBmV/Ch
XMOD	XMOD		-	-70	1	
DC Current		mA	-	130	-	Vdd = 8.0V

#### Note

### **Absolute Maximum Ratings**

PARAMETER	UNIT	MIN	ТҮР	MAX
Device Voltage	VDC	-	8	12
Operating Case Temperature	°C	-40	-	85
Storage Temperature	°C	-40	-	150
ESD Human Body Model	-	-	Class 1A	-
Moisture sensitivity Level	-	-	MSL1	-
Junction temperature	°C	-	-	180
Thermal Resistance (Rth)	°C/W	-	70	-

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<sup>1.</sup> Test conditions unless otherwise noted. Test Freq = 500MHz, T=25  $^{\circ}\!\!\mathrm{C}$  , Vdd=8V, 75  $\!\Omega$  system

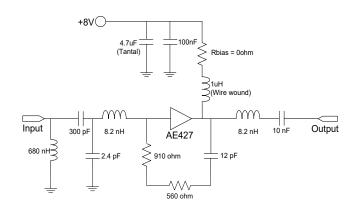
<sup>2.</sup> OIP3 measured with 2 tones at an output power of +5dBm/tone separated by 1MHz, Test Freq = 500MHz

# **AE427**

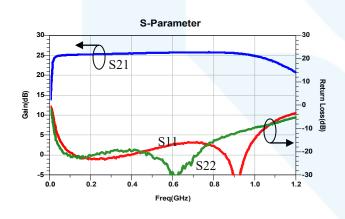


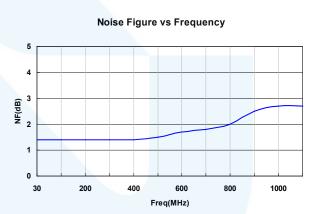
### **Application Circuit** @ 30 ~ 1000MHz, 75ohm System

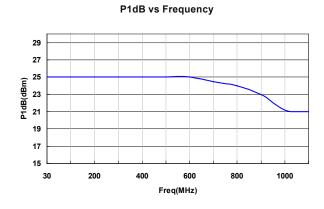
PARAMETER	UNIT	TYPICAL			
Frequency	MHz	30	500	1000	
Gain(S21)	dB	25	25.3	24.9	
IRL(S11)	dB	-17 -12		-16.5	
ORL(S22)	dB	-18.8 -16		-11.5	
Output IP3	dBm	41	41	40	
P1dB	dBm	25	25	21.2	
Noise Figure	dB	1.4	1.5	2.7	
CSO(1)	dBc				
CTB(1)	dBc	-71			
XMOD(1)	dBc	-70			
Current	mA	130			

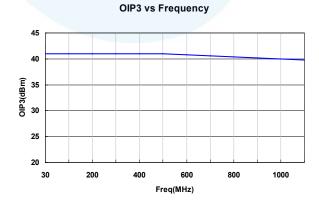


## **Typical Performance** @ VDD=8V, IDS=130mA, T=25 ℃, 75ohm System









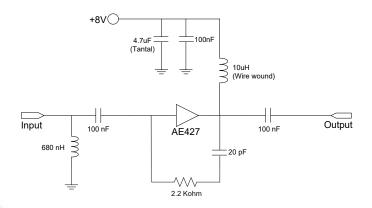
<sup>(1) 135</sup>channels, +30dBmV/ch

# **AE427**

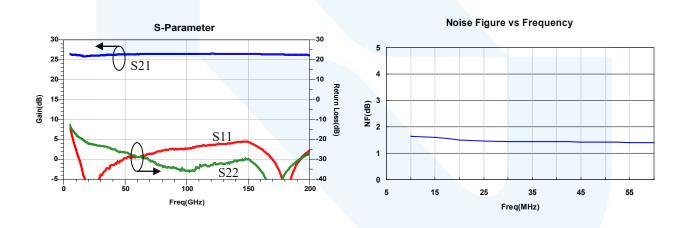


## **Application Circuit** @ 5 ~ 200MHz, 75ohm System

PARAMETER	UNIT	TYPICAL			
Frequency	MHz	5 25		50	
Gain(S21)	dB	26.5	26	26.2	
IRL(S11)	dB	-13 -45		-30	
ORL(S22)	dB	-12 -23		-27	
Output IP3	dBm	28.5 39		39	
P1dB	dBm	24.5	25	25	
Noise Figure	dB	1.0 1.5		2.7	
CSO(1)	dBc	-60			
CTB(1)	dBc	-74			
XMOD(1)	dBc	-65			
Current (1) Schomolo   45 dPmV/o	mA	130			



## **Typical Performance** @ VDD=8V, IDS=130mA, T=25 °C, 75ohm System



## Multi-Tone Test: 8CH\_FLAT@Output Power +45dBmV/Ch

	Level: +45dBmV Tilt: 8CH_FLAT									
FRQ	XMD (NCTA)	CTB RAW	CTB COR	N-FLR	CSU RAW	CSU COR	CSU FRQ	CSL RAW	CSL COR	CSL FRQ
7	65.6	73.8	74.1	86.4	85.7	90.1	7.65	60.6	60.6	5.99
31	65.4	74.2	74.2	91.5	60.2	60.2	31.99	61.1	61.1	29.99
49	65.2	75.3	75.4	91.4	60.6	60.6	49.99	90.4	94.7	47.97
Min	65.2	73.8	74.1	86.4	60.2	60.2	7.65	60.6	60.6	5.99
Max	65.6	75.3	75.4	91.5	85.7	90.1	49.99	90.4	94.7	47.97

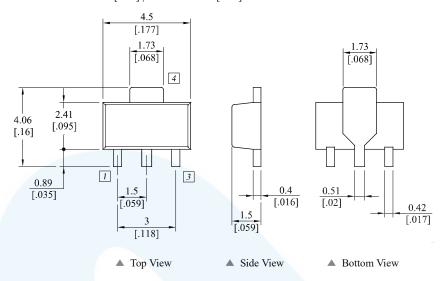
<sup>(1) 8</sup>channels, +45dBmV/ch

## **AE427**



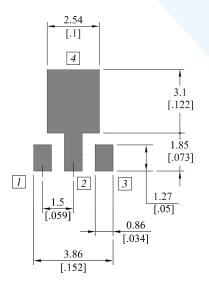
## Package Dimensions (Type: SOT-89)

\* Unit: mm[inch] | Tolerance ±0.2[.008]

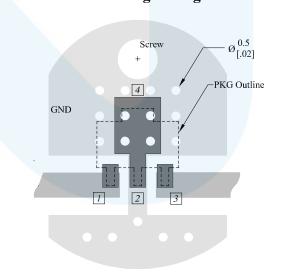


Pin Description								
Pin No	Function	Pin No	Function					
1	Input	4	GND					
2	GND	-	-					
3	Output / Bias	-	-					

#### **Recommended Pattern**



### **Recommended Mounting Configuration**



#### \* Mounting Configuration Notes

- 1. Ground / thermal via holes are critical for the proper performance of this device.
- 2. Add as much copper as possible to inner and outer layers near the part to ensure optimal thermal performance.
- 3. Mounting screws can be added near the part to fasten the board to a heatsink. Ensure that the ground / thermal via hole region contacts the heatsink.
- 4. Do not put solder mask on the backside of the PCB in the region where the board contacts the heatsink.
- 5. RF trace width depends upon the PCB material and construction.
- 6. Use 1 oz. Copper minimum.

## **AE427**



### **Revision History**

Part Number	Release Date	Version	Modification	Data Sheet Status
AE427	2014.04.22	1.2	Absolute Maximum Ratings (Delete Tj Typ)	-
AE427	2012.10.15	1.1	New datasheet format	-



#### Certification

This product is manufactured by a company that is certified for the AS9100D quality management system.

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